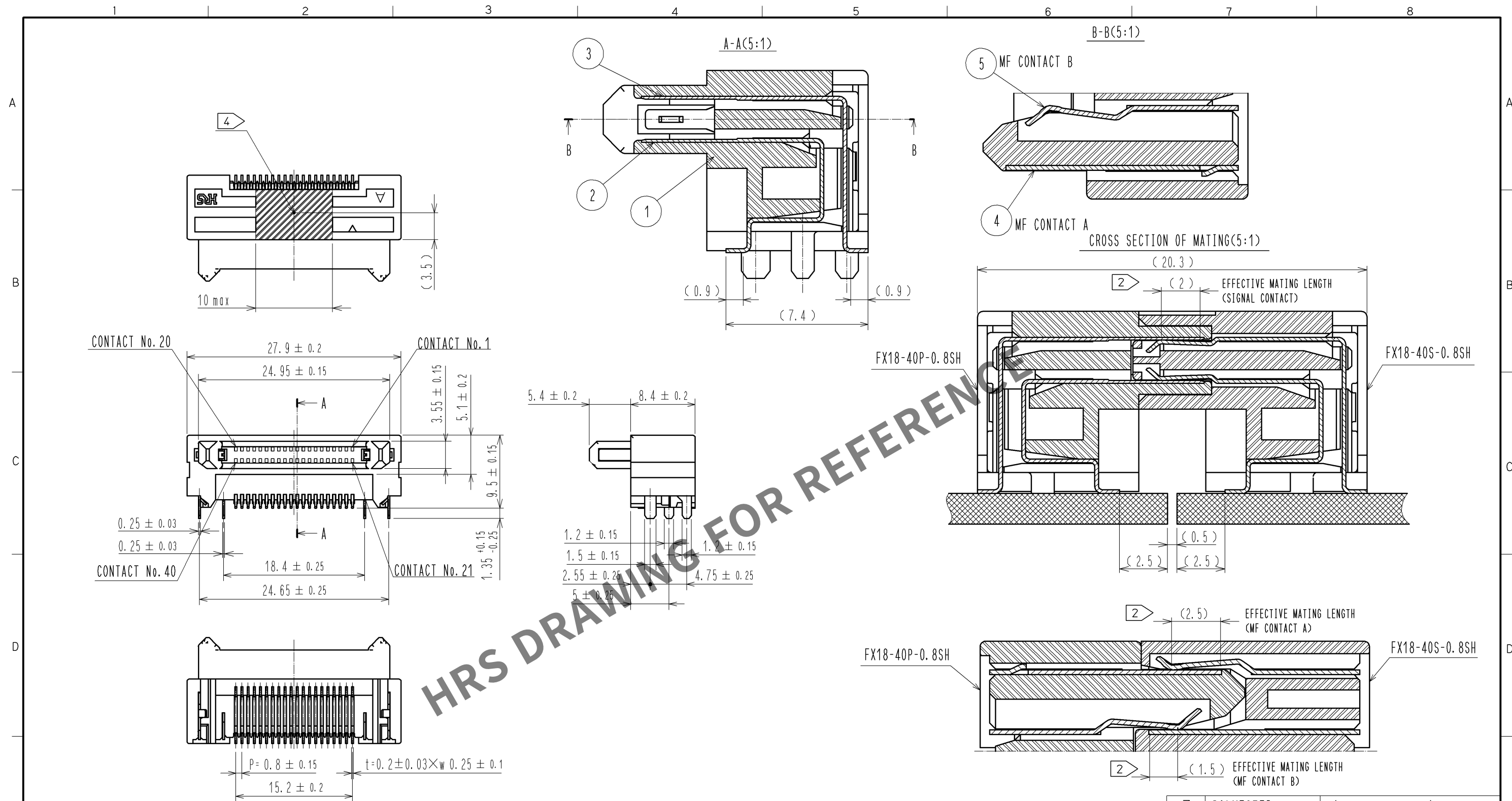
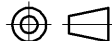




NOTE 1 LEAD CO—PLANARITY IS 0.1mm MAX.

- 2 CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B)
WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
- 3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
- 4 IT SHOWS CONNECTOR'S CENTRE OF GRAVITY AND VACUUM PICKUP AREA.
- 5 PACKING FOR PRODUCT APPLIES EMBOSSED CARRIER TAPE PACKING. (300pcs/RL)
- 6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
- 7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.
- 1 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES.
BE SURE TO CONNECT TO THE SAME CIRCUIT.

			7	POLYESTER	(EMBOSSSED COVER TAPE)		
3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1μm	6	POLYSTYRENE	(EMBOSSSED CARRIER TAPE)		
		LEAD AREA:GOLD 0.03μm	5	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1μm		
		UNDER PLATING:NICKEL 1.3μm			LEAD AREA:TIN-PLATING 1μm		
2	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1μm	4	PHOSPHOR BRONZE	UNDER PLATING:NICKEL 1.3μm		
		LEAD AREA:GOLD 0.03μm			CONTACT AREA:GOLD 0.1μm		
		UNDER PLATING:NICKEL 1.3μm			LEAD AREA:TIN-PLATING 1μm		
1	POLYAMIDE	BLACK UL94V-0			UNDER PLATING:NICKEL 1.3μm		
NO.	MATERIAL	FINISH . REMARKS		NO.	MATERIAL	FINISH . REMARKS	

UNITS mm		SCALE 2 : 1		COUNT 5	DESCRIPTION OF REVISIONS DIS-F-005578	DESIGNED TH. SANO	CHECKED KI. HIROKAWA	DATE 11. 07. 21
 HIROSE ELECTRIC CO., LTD.		APPROVED : HS. OKAWA		09. 10. 13	DRAWING NO. EDC3-159074-02			
		CHECED : KI. HIROKAWA		09. 10. 13	PART NO. FX18-40P-0. 8SH(11)			
		DESIGNED : TH. SANO		09. 10. 13	CODE NO. CL579-0002-5-11			
		DRAWN : TH. SANO		09. 10. 13				
				 				

